



## Mitsuya Co.,Ltd.

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1 November 2021

### Mitsuya Co. Ltd. Exhibits at the FiO+LS Frontiers in Optics and laser Science Conference Virtually.

Mitsuya provides an advanced engineering solution for improving various plating and finishing functions and of industrial products.

In this exhibition, we would like to showcase two of our key plating technologies essential for the silicon photonics industry.

First, we would like to introduce our gold-tin alloy plating.

Gold-tin alloy solder is used for RF components and optical communication related components that require high reliability.

Mitsuya's gold-tin alloy deposits as a RoHS-compliant lead-free solder for high-temperature connection, and as a solder for high-strength and high-reliability connections.

Next, we would like to present our wafer bump plating technology.

This plating from Mitsuya is used for flip chips for smartphones. Electroless nickel, electroless gold, palladium, tin, etc. can be formed on the upper layer of the pillar.

To find out more about the above platings or the other platings that we offer please contact our representatives who will exhibit at this exhibition.

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